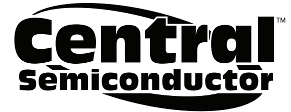
Material Composition Specification

DFN5X6 Case



Device average mass . . . . 0.07304 g

Fluctuation margin . . . . +/-10%

Component	Material		Substance	CAS No.	Substance		
	Name	(%wt)			(mg)	(%wt)	(ppm)
Lead Frame	Ag plated Cu C194	0.01800	Cu	7440-50-8	17.39	96.590	238068
			Fe	7439-89-6	0.406	2.256	5560
			Pb	7439-92-1	0.0005	0.003	7
			P	7723-14-0	0.0043	0.024	59
			Zn	7440-66-6	0.023	0.127	313
			Ag	7440-22-4	0.180	1.000	2465
Die	Silicon	0.00551	Si	7440-21-3	5.505	100	75372
Die attach material	Conductive Epoxy HT2VP1	0.00134	Ag	7440-22-4	1.178	88.0	16131
			Glycol Ether	-	0.0803	6.0	1100
			$C_{12}H_{22}O_4$	16096-31-4	0.0803	6.0	1100
Wire	Gold	0.00104	Au	7440-57-5	1.043	99.99	14275
			Other	-	0.0001	0.01	1
Lead finish	Alloy	0.001712	Sn	7440-31-5	1.711	99.99	23428
			Other	-	0.0002	0.01	2
Encapsulation	Epoxy Resin G700LTD	0.04544	Epoxy Resin	Proprietary	1.363	3	18664
			Phenol Resin	Proprietary	1.363	3	18664
			Silica A	60676-86-0	34.99	77	479031
			Silica B	7631-86-9	6.679	14.7	91451
			Metal Hydroxide	Proprietary	0.909	2	12442
			C (Black)	1333-86-4	0.136	0.3	1866
Total		0.07304					

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (15-March 2024)